

LASER PROCESSING APPARATUS

ABSTRACT

There is provided a laser processing apparatus that processes a workpiece by irradiation with a laser beam. The laser processing apparatus includes a holding unit including a holding surface that holds the workpiece and a laser irradiation unit that irradiates the workpiece held by the holding unit with the laser beam. The laser irradiation unit includes a laser oscillator, a collecting lens that focuses the laser beam emitted from the laser oscillator, and a foreign matter adhesion preventing unit that prevents adhesion of a foreign matter to the collecting lens.

[Fig. 3]